



Material Content Data Sheet



Sales Product Name		BTS4300SGA		Issued		19. January 2018			
MA#		MA001427276							
Package		PG-DSO-8-24		Weight*		83.23 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.539	1.85	1.85	18487	18487	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108		
	non noble metal	zinc	7440-66-6	0.036	0.04		431		
	non noble metal	iron	7439-89-6	0.717	0.86		8617		
wire	non noble metal	copper	7440-50-8	29.121	34.99	35.90	349903	359059	
	noble metal	gold	7440-57-5	0.471	0.57	0.57	5660	5660	
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1184	
plastics	plastics	epoxy resin	-	4.532	5.45		54456		
	inorganic material	silicondioxide	60676-86-0	44.632	53.62	59.19	536270	591910	
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9779	9779	
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7813	7813	
glue	plastics	epoxy resin	-	0.106	0.13		1276		
	noble metal	silver	7440-22-4	0.501	0.60	0.73	6016	7292	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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